Page 8, line 24, replace the paragraph beginning there at with:

The conductive strips 44 and 46 can be formed by initially masking off all surfaces of the package housing, except the edge 49 of the first bond shelf 18 with a plating resist maskant 50, as shown in Figure 5. The masked housing can then be dipped into a plating bath 52 as shown in Figure 5. The plating bath 52 plates a conductive material such as copper onto the edge 49 of the first bond shelf 18. The maskant 50 is then removed and the notches 48 can be drilled into the edges of the first bond shelf 18 to separate the plated material into the first and second conductive strips 44 and 46. All exposed copper surfaces may then be plated with gold.

In the Claims

Please amend claims 13-15, and 17 as follows below.

Please cancel claims 21-34 without prejudice.

Please add new claims 35-49 as follows below.

Please accept a clean version of the entire set of pending claims including the amendments made herein.

Clean Version of Pending Claims

1-12. (Cancelled)

13. (Amended Thrice) A method for assembling an electronic package, comprising:

forming a housing which has a bond pad located on a first surface of a bond shelf, the bond shelf having a second surface along a thickness of the bond shelf;

forming a conductive strip along the second surface of the bond shelf; and

removing a portion of the conductive strip along the second surface of the bond shelf to form a pair of separate conductive strips along the second surface of the bond shelf.

14. (Amended Twice) The method as recited in claim 13, wherein the conductive strip is formed by plating a conductive material onto the second surface of the bond shelf.

15. (Amended Twice) The method as recited in claim 13, wherein the portion of the conductive strip is removed by

drilling a portion of the second surface of the bond shelf including the conductive strip.

16. (Amended Once) The method as recited in claim 13, further

comprising:

mounting an integrated circuit to the housing and connecting the integrated circuit to the bond pad.

17. (Amended Twice) The method as recited in claim 14, wherein the portion of the conductive strip is removed by

etching away a portion of the conductive material on the second surface of the bond shelf.

18. (Amended Once) The method as recited in claim 13, wherein the conductive strip is formed along the second surface of the bond shelf by

masking all surfaces of the bond shelf except for the second surface of the bond shelf, and

plating a conductive material onto the second surface of the bond shelf.

19. (Unamended) The method as recited in claim 18, wherein the conductive material is copper, and

the conductive strip is further formed by plating gold onto the copper.

20. (Unamended) The method as recited in claim 19, wherein the portion of the conductive strip is removed by

drilling a portion of the bond shelf.

21-34. (Cancelled)

35. (New) The method as recited in claim 13, wherein the forming of the conductive strip further includes forming a portion of the conductive strip around onto the first surface of the bond shelf to couple to the bond pad on the first surface of the bond shelf.

36. (New) The method as recited in claim 35, wherein the portion of the conductive strip around on the first surface of the bond shelf to further anchor the conductive strip to the housing.

37. (New) The method as recited in claim 13, wherein the forming of the conductive strip further includes forming a portion of the conductive strip around onto the first surface of the bond shelf to form another bond pad on the first surface of the bond shelf.

38. (New) The method as recited in claim 37, wherein the portion of the conductive strip around on the first surface of the bond shelf to further anchor the conductive strip to the housing.

39. (New) A method for assembling an electronic package, comprising:

forming a housing which has a bond pad located on a top surface of a bond shelf, the bond shelf having a side surface along an edge of the bond shelf;

plating a conductive material along the side surface of the bond shelf; and

removing a portion of the conductive material along the side surface of the bond shelf to form a pair of separate conductive strips along the side surface of the bond shelf.

40. (New) The method of claim 39, wherein

the portion of the conductive material is removed by drilling into the edge of the bond shelf including the conductive material and the side surface.

41. (New) The method of claim 39, wherein

the portion of the conductive material is removed by etching away a portion of the conductive material from the side surface of the bond shelf.

42. (New) The method of claim 39, wherein,

the plating of the conductive material onto the side surface of the bond shelf includes

masking surfaces of the housing that are not to be plated and

leaving surfaces of the housing unmasked that are to be plated, including the side surface of the bond shelf that is to be plated.

43. (New) The method of claim 42, wherein

the plating of the conductive material further includes

plating copper onto the unmasked surfaces of the housing, and

plating gold onto the copper.

44. (New) The method of claim 39, wherein

the portion of the conductive material is removed by

drilling into the edge of the bond shelf including the conductive material and the side surface.

45. (New) The method of claim 39, wherein

the plating of the conductive material further includes

plating a portion of the conductive material from the side surface around onto the top surface of the bond shelf to couple to the bond pad on the top surface of the bond

shelf.

46. (New) The method of claim 45, wherein the portion of the conductive material plated around onto the first surface of the bond shelf to further anchor the conductive material to the housing.

E5 cancel

47. (New) The method of claim 39, wherein the plating of the conductive material further includes plating a portion of the conductive material from the side surface around onto the top surface of the bond shelf to form another bond pad on the top surface of the bond shelf.

48. (New) The method of claim 47, wherein the portion of the conductive material plated around onto the top surface of the bond shelf to further anchor the conductive material to the housing.

49. (New) The method of claim 39, further comprising: mounting an integrated circuit to the housing and connecting the integrated circuit to the bond pad.